

SA.45s RoHS CSAC Options 001 and 003

RoHS-Compliant Chip-Scale Atomic Clock

CSAC

Microsemi invented portable atomic timekeeping with the world's first family of miniature and chip scale atomic clocks.

Choose CSAC for best-in-class stability, size, weight, and power consumption.



Features

- Power consumption <120 mW
- Less than 17 cc volume, 1.6" × 1.39" × 0.45"
- 10 MHz CMOS-compatible output
- 1PPS output and 1PPS input for synchronization
- RS-232 interface for monitoring and control
- Short term stability (Allan Deviation) of 3.0×10^{-10} at $\tau = 1$ sec
- RoHS 2 (Directive 2011/65/EU)
- Wide storage temperature: 100 °C

Now available in a RoHS-compliant form, the Microsemi SA.45s Chip-Scale Atomic Clock (CSAC) brings the accuracy and stability of an atomic clock to portable applications while maintaining low power consumption (120 mW) and volume (<17 cc).

The SA.45s provides RF and 1PPS outputs at standard CMOS levels, with short-term stability (Allan Deviation) of 3.0×10^{-10} at $\tau = 1$ sec, typical long-term aging of $<9 \times 10^{-10}$ /month, and maximum frequency change of $\pm 5 \times 10^{-10}$ over an operating temperature range of -10 °C to 70 °C.

The SA.45s CSAC accepts a 1PPS input that may be used to synchronize the unit's 1PPS output to an external reference clock with ± 100 ns accuracy. It also use the 1PPS input to discipline its phase and frequency to within 1 ns and 1.0×10^{-12} , respectively.

A standard CMOS-level RS-232 serial interface is built in to the SA.45s. This is used to control and calibrate the unit and also to provide a comprehensive set of status monitors. The interface is also used to set and read the CSAC's internal time-of-day clock.

Applications¹

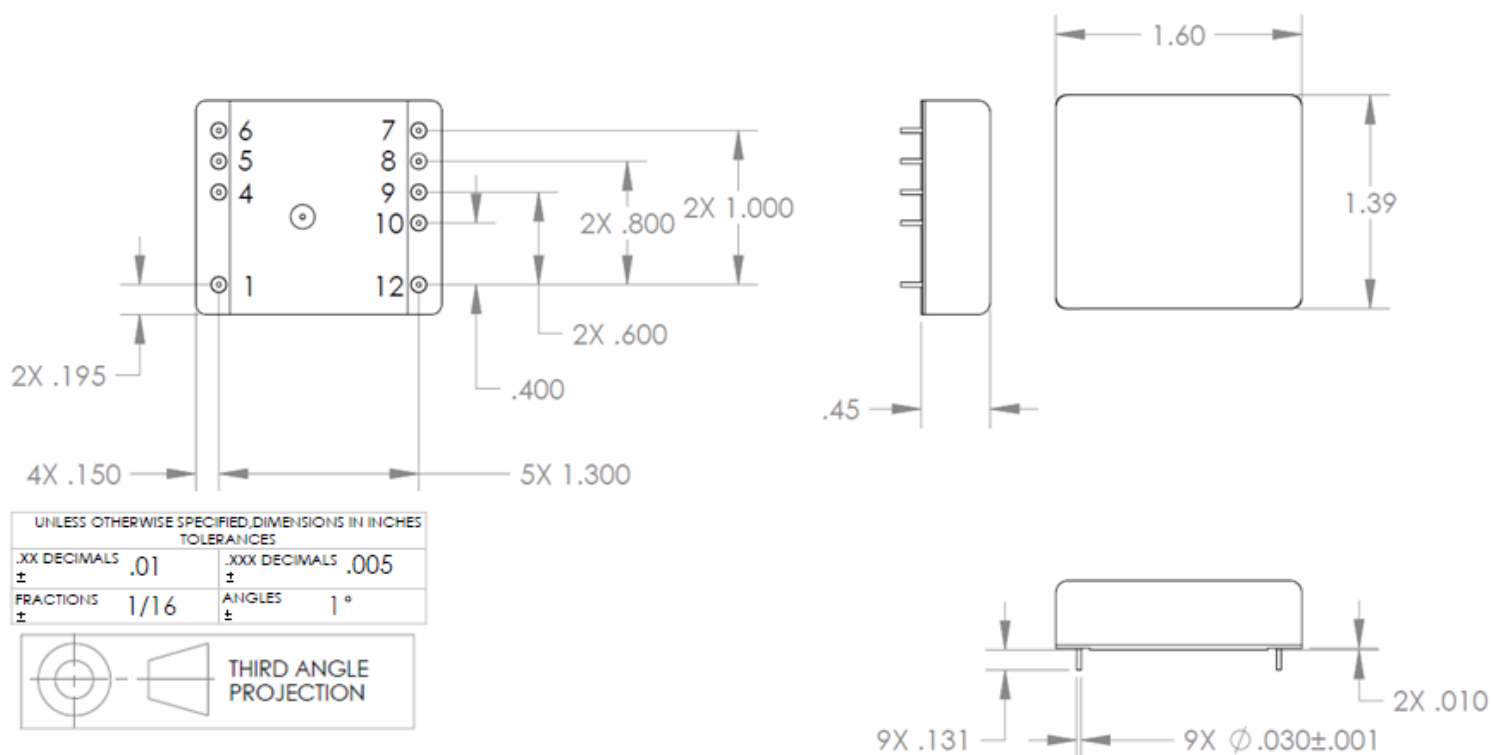
- GPS receivers
- Backpack radios
- Anti-IED jamming systems
- Autonomous sensor networks
- Unmanned vehicles
- Underwater sensor systems
- Stability for various other communication and transmission applications

¹The CSAC is not tested, qualified, or rated for space applications.

SA.45s RoHS CSAC Options 001 and 003

RoHS-Compliant Chip-Scale Atomic Clock

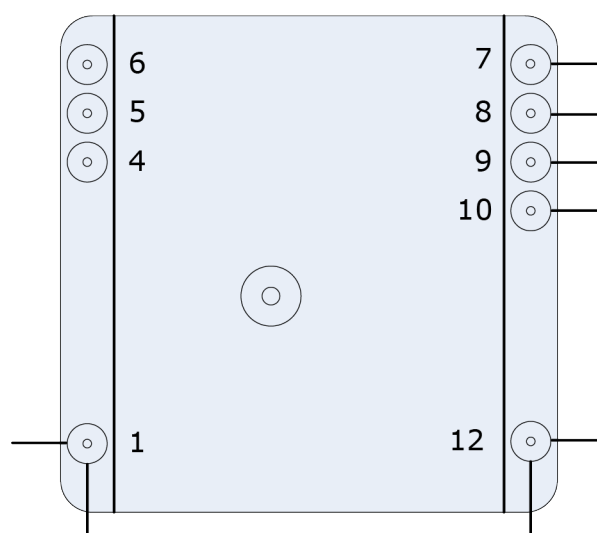
Mechanical Interface



Pin Description

Pin Number	I.D.
1	Tune
2	N/A
3	N/A
4	BITE
5	Tx
6	Rx
7	Vcc
8	GND
9	1PPS IN
10	1PPS OUT
11	N/A
12	RF OUT

Bottom View



SA.45s RoHS CSAC Options 001 and 003

RoHS-Compliant Chip-Scale Atomic Clock

Specifications¹

Electrical

RF Output

- Frequency 10 MHz (Option 001)
16.384 MHz (Option 003)
- Format CMOS
- Amplitude 0 V to V_{CC}
- Load impedance 1 MΩ
- Quantity 1

1PPS Output

- Rise/fall time (10%–90%) at load capacitance 10 pF <10 ns
- Pulse width 100 μs (Option 001)
97.656 μs (Option 003)
- Level 0 V to V_{CC}
- Logic high (V_{OH}) minimum 2.80 V
- Logic low (V_{OL}) max 0.30 V
- Load impedance 1 MΩ
- Quantity 1

1PPS Input

- Format Rising edge
- Low level <0.5 V
- High level 2.5 V to V_{CC}
- Input impedance 1 MΩ
- Quantity 1

Serial Communications

- Protocol RS232
- Format CMOS 0 V to V_{CC}
- Tx/Rx impedance 1 MΩ
- Baud rate 57600

Built-in Test Equipment (BITE) Output

- Format CMOS 0 V to V_{CC}
- Load impedance 1 MΩ
- Logic 0 = Normal operation
1 = Alarm

Power Input

- Operating <120 mW
- Warmup <140 mW
- Input voltage (V_{CC}) 3.3 ± 0.1 V_{DC}

Environmental

- Operating temperature –10 °C to 70 °C
- Maximum frequency change over operating temp range (maximum rate of change 0.5 °C per minute) ±5 × 10⁻¹⁰
- Frequency change over allowable input voltage range ±4 × 10⁻¹⁰
- Magnetic sensitivity (≤2.0 Gauss) ±9 × 10⁻¹¹/Gauss
- Radiated emissions Compliant to FCC part 15, Class B, when mounted properly onto host PCB
- Vibration Maintains lock under MIL-STD-810, Method 514.5, Procedure 1, 7.7 g_{rms}
- Humidity 0%–95% RH per MIL-STD-810, Method 507.4

Storage and Transport (Non-operating)

- Temperature –55 °C to 100 °C
- Vibration MIL-STD-810, Method 514.5, Procedure 1, 7.7 g_{rms}
- Shock (1 ms half-sine) 1000 g

Performance Parameters

- Warm-up time <180 s
- Analog tuning Range: ±2.2 × 10⁻⁸
Resolution: 1 × 10⁻¹¹
Input: 0 V–2.5 V into 100 kΩ
- Digital tuning Range: ±1 × 10⁻⁶
Resolution: 1 × 10⁻¹²

Phase Noise (SSB)

Frequency	Option 001	Option 003
1 Hz	<-50 dBc/Hz	<-46 dBc/Hz
10 Hz	<-70 dBc/Hz	<-66 dBc/Hz
100 Hz	<-113 dBc/Hz	<-104 dBc/Hz
1 kHz	<-128 dBc/Hz	<-128 dBc/Hz
10 kHz	<-135 dBc/Hz	<-135 dBc/Hz
100 kHz	<-140 dBc/Hz	<-140 dBc/Hz

Frequency Accuracy

- Maximum offset at shipment ±5 × 10⁻¹¹
- Maximum retrace (48 hrs off) ±5 × 10⁻¹⁰
- 1PPS sync ±100 ns

¹At input voltage V_{CC} = 3.3 V_{DC} and ambient temperature = 25 °C, unless otherwise specified.

SA.45s RoHS CSAC Options 001 and 003

RoHS-Compliant Chip-Scale Atomic Clock

Aging

Type ²	SA.45s ³
Monthly	$<9 \times 10^{-10}$
Yearly	$<1 \times 10^{-8}$

²After 30 days of continuous operation.

³All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.

Short-Term Stability (Allan Deviation)

Type	SA.45s
$\tau = 1 \text{ s}$	3×10^{-10}
$\tau = 10 \text{ s}$	1×10^{-10}
$\tau = 100 \text{ s}$	3×10^{-11}
$\tau = 1000 \text{ s}$	1×10^{-11}

Physical

- Weight $<35 \text{ g}$ ($<1.23 \text{ oz}$)
- Size $1.6" \times 1.39" \times 0.45"$
- MTBF $>100,000 \text{ hours}$
- RoHS RoHS 2 (Directive 2011/65/EU)

Solder

Hand solder operation should have a maximum solder tip temperature of $370 \text{ }^\circ\text{C}$ ($698 \text{ }^\circ\text{F}$) and a dwell time of $<5 \text{ s}$.

Ordering Information

Part Number	Description	Output Frequency
090-03240-001	RoHS-compliant chip-scale atomic clock option 001	10 MHz
090-03240-003	RoHS-compliant chip-scale atomic clock option 003	16.384 MHz



Microsemi Corporate Headquarters
 One Enterprise, Aliso Viejo, CA 92656 USA
 Within the USA: +1 (800) 713-4113
 Outside the USA: +1 (949) 380-6100
 Fax: +1 (949) 215-4996
 Email: sales.support@microsemi.com
www.microsemi.com

©2016–2018 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions, security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, California and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.